| - | 1081225 | substrate or chip or lot or wafer or semiconductor | USPAT; | Time stamp 2004/08/20 15:17 |
|-----|---------|--|-----------|-----------------------------|
| | | | | |
| | | | US-PGPUB; | |
| | | | IBM TDB | |
| - 1 | 31499 | (substrate or chip or lot or wafer or semiconductor) and (defect\$1 same | USPAT; | 2004/08/11 14:04 |
| i | | substrate) | US-PGPUB; | |
| | | , | IBM TDB | |
| _ | 488 | ((substrate or chip or lot or wafer or semiconductor) and (defect\$1 | USPĀT; | 2004/08/11 14:04 |
| | ,,,, | same substrate)) and (optical near1 inspect\$3) | US-PGPUB; | 2001/00/11 11:01 |
| | | oune substitue)) und (option hour mapocups) | IBM TDB | |
| _ | 160 | (((substrate or chip or lot or wafer or semiconductor) and (defect\$1 | USPĀT; | 2004/08/11 14:05 |
| | 100 | same substrate)) and (optical near1 inspect\$3)) and (defect\$1 near1 | US-PGPUB; | 2004/00/11 14.03 |
| | | locat\$4) | IBM TDB | |
| _ | 65 | ((((substrate or chip or lot or wafer or semiconductor) and (defect\$1 | USPAT; | 2004/08/11 14:31 |
| | 05 | same substrate)) and (optical near1 inspect\$3)) and (defect\$1 near1 | US-PGPUB; | 2004/06/11 14.31 |
| | | locat\$4)) and (cluster\$1 or signature\$1) | IBM TDB | |
| | 0 | | - | 2004/09/11 14:21 |
| - | U | defect\$1 adj by adj location | USPAT; | 2004/08/11 14:31 |
| | | | US-PGPUB; | |
| | 1170 | 1.6 .61 141 | IBM_TDB | |
| - | 1179 | defect\$1 adj1 location | USPAT; | 2004/08/11 14:32 |
| | | | US-PGPUB; | |
| | | | IBM_TDB | |
| - | 23 | (((((substrate or chip or lot or wafer or semiconductor) and (defect\$1 | USPAT; | 2004/08/12 19:09 |
| | | same substrate)) and (optical near1 inspect\$3)) and (defect\$1 near1 | US-PGPUB; | |
| | | locat\$4)) and (cluster\$1 or signature\$1)) and (((substrate or chip or lot | IBM_TDB | |
| | | or wafer or semiconductor) and (defect\$1 same substrate)) and | _ | |
| | | (defect\$1 adj1 location)) | | |
| - | 227 | ((substrate or chip or lot or wafer or semiconductor) and (defect\$1 | USPAT; | 2004/08/20 15:59 |
| | | same substrate)) and (defect\$1 adj1 location) | US-PGPUB; | |
| | | • | IBM_TDB | |
| - | 227 | ((substrate or chip or lot or wafer or semiconductor) and (defect\$1 | USPĀT; | 2004/08/16 15:35 |
| | | same substrate)) and (defect\$1 adj1 location) | US-PGPUB; | |
| | | (| IBM TDB | |
| _ | 16749 | (bound\$3 near1 (box or area)) | USPAT; | 2004/08/16 15:39 |
| | 10.15 | (country) | US-PGPUB; | 2004/00/10 13.39 |
| | | | IBM TDB | |
| _ | 8 | (((substrate or chip or lot or wafer or semiconductor) and (defect\$1 | USPAT; | 2004/08/16 15:36 |
| ľ | J | same substrate)) and (defect\$1 adj1 location)) and ((bound\$3 near1 | US-PGPUB; | 2004/06/10 13.30 |
| | | (box or area))) | IBM TDB | |
| _ | 3389 | bound\$3 near1 box | USPAT; | 2004/08/20 15:59 |
| | 3367 | bounds hear box | | 2004/06/20 13:39 |
| | | | US-PGPUB; | |
| _ | 36827 | (inspect\$3 or detect\$3) same defect\$1 | IBM_TDB | 2004/09/16 15 10 |
| - | 30827 | (mspecips of defectps) same defectpt | USPAT; | 2004/08/16 15:40 |
| | | | US-PGPUB; | |
| | 175 | (hound\$2 moon1 how) and ((inamost\$2 1\$2) 1.5\$1) | IBM_TDB | 2004/00/20 15 :: |
| - | 175 | (bound\$3 near1 box) and ((inspect\$3 or detect\$3) same defect\$1) | USPAT; | 2004/08/20 15:44 |
| | | | US-PGPUB; | |
| | 110.405 | along the state of | IBM_TDB | |
| - | 112407 | signature\$1 or cluster | USPAT; | 2004/08/16 15:40 |
| | | | US-PGPUB; | |
| | | | IBM_TDB | |
| - | 78 | ((bound\$3 near1 box) and ((inspect\$3 or detect\$3) same defect\$1)) and | USPAT; | 2004/08/16 15:41 |
| 1 | | (signature\$1 or cluster) | US-PGPUB; | |
| | | | IBM_TDB | |
| - | 156 | reticle and mask and monolithic | USPĀT; | 2004/08/20 15:27 |
| | | | US-PGPUB; | |
| | | | IBM_TDB | |
| - | 4 | (reticle and mask and monolithic) and (optical near1 inspection) | USPĀT; | 2004/08/20 15:28 |
| | | , , , , | US-PGPUB; | |
| | | | IBM TDB | |
| _ | 3395 | bound\$3 near1 box | USPAT; | 2004/08/20 15:59 |
| - 1 | | | | 1 -00 ., 00, 20 13.33 |
| | l | | US-PGPUB; | |

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| - | 1334 | (bound\$3 near1 box) and overlap | USPAT; | 2004/08/20 15:59 |
|---|------|--|-----------|------------------|
| | | | US-PGPUB; | } |
| | | | IBM_TDB | |
| - | 228 | ((substrate or chip or lot or wafer or semiconductor) and (defect\$1 | USPAT; | 2004/08/20 16:00 |
| | | same substrate)) and (defect\$1 adj1 location) | US-PGPUB; | |
| | 1 | | IBM_TDB | |
| - | 0 | ((bound\$3 near1 box) and overlap) and (((substrate or chip or lot or | USPAT; | 2004/08/20 15:59 |
| | | wafer or semiconductor) and (defect\$1 same substrate)) and (defect\$1 | US-PGPUB; | |
| | | adj1 location)) | IBM_TDB | |
| - | 635 | ((bound\$3 near1 box) and overlap) and (substrate or chip or lot or | USPAT; | 2004/08/20 16:00 |
| | | wafer or semiconductor) | US-PGPUB; | |
| | | | IBM_TDB | |
| - | 95 | (((bound\$3 near1 box) and overlap) and (substrate or chip or lot or | USPAT; | 2004/08/20 16:12 |
| | | wafer or semiconductor)) and defect | US-PGPUB; | |
| | | | IBM_TDB | |
| - | 6 | (correlat\$3 near1 defect\$1) and (position near1 stage) | USPAT; | 2004/08/21 13:13 |
| | | | US-PGPUB; | |
| | | | IBM_TDB | |